

CoolMOS IC Market By Type (Through-hole, Surface-mount) , By End User (Automotive, Industrial, Consumer Electronics, Telecommunication, Medical, Others) : Global Opportunity Analysis and Industry Forecast, 2024-2032

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Abstracts

CoolMOS IC Market

The coolMOS IC market was valued at \$2.6 billion in 2023 and is projected to reach \$4.1 billion by 2032, growing at a CAGR of 5.3% from 2024 to 2032.

Cool metal-oxide-semiconductor (MOS) integrated circuit (IC) is a semiconductor device assimilated with the combination of metal-oxide-semiconductor field-effect transistors and cooling technologies. Developed by Infineon Technologies—a German semiconductor manufacturer—the IC offers high energy efficiency & reduces power loss in electronic applications with power conversion and power management circuits. The key attributes of coolMOS ICs include instant switching speeds, low gate charge, high voltage-handling capacity, and low requirements for thermal management. These ICs find applications in power supply units, renewable energy systems, switching regulators, electric vehicles (EVs), and industrial automation.

Increase in energy saving and sustainability initiatives has fueled the demand for semiconductors that reduce energy losses in electrical applications, which acts as a key driver of the coolMOS IC market. In addition, exponential rise in the adoption of EVs for commercial and personal usage is propelling the development of the market. Furthermore, expansion of the consumer electronics and telecommunication industries is augmenting the market growth owing to surge in requirement for high-power density semiconductors. In recent times, the development of wide bandgap semiconductors

such as silicon carbide and gallium nitride is trending in the market as these semiconductors effectively cater to electronic systems that require high-power densities and fast switching speeds.

However, the usage of cutting-edge materials and technologies in coolMOS ICs increases their overall price, which limits their adoption in small-scale industries & budget-friendly consumer electronics and hampers the development of the market. Moreover, coolMOS ICs generate a considerable amount of electronic waste at the end of the lifecycle, hence upsurging concerns among environmentally inclined individuals and restraining the market growth. On the contrary, the integration of coolMOS ICs into the grid system of renewable energy sources is expected to open new avenues for the market owing to rise in the utility of renewable energy. According to the International Energy Agency, the consumption of renewable energy in the power, heat, and transport sectors is projected to increase by 60% by 2030. Therefore, the market is poised to witness lucrative opportunities due to the pivotal role of coolMOS ICs in power conversion and battery management systems of renewable energy infrastructure.

Segment Review

The coolMOS IC market is segmented into type, end user, and region. On the basis of type, the market is bifurcated into through-hole and surface-mount. Depending on end user, it is classified into automotive, industrial, consumer electronics, telecommunication, medical, and others. Region wise, it is analyzed across North America, Europe, Asia-Pacific, and LAMEA.

Key Findings

On the basis of type, the surface-mount segment held a notable share of the market in 2023.

Depending on end user, the consumer electronics segment dominated the market in 2023.

Region wise, Asia-Pacific was the highest revenue generator in the market in 2023.

Competition Analysis

The major players in the global coolMOS IC market include Infineon Technologies AG, NXP Semiconductors, STMicroelectronics, ON Semiconductor Corporation, Texas

Instruments, Toshiba, Renesas Electronics, ROHM Semiconductor, Vishay Intertechnology Inc., and Mitsubishi Electric Corporation. These major players have adopted various key development strategies such as business expansion, new product launches, and partnerships to strengthen their foothold in the competitive market.

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Market share analysis of players by products/segments

Regulatory Guidelines

Historic market data

Key Market Segments

By Type

Through-hole

Surface-mount

By End User

Automotive

Industrial

Consumer Electronics

Telecommunication

Medical

Others

By Region

North America

U.S.

Canada

Mexico

Europe

France

Germany

Italy

UK

Rest of Europe

Asia-Pacific

China

Japan

India

South Korea

Rest of Asia-Pacific

LAMEA

Latin America

Middle East

Africa

Key Market Players

Infineon Technologies AG

Infineon Technologies AG

NXP Semiconductors

NXP Semiconductors

STMicroelectronics

STMicroelectronics

ON Semiconductor Corporation

ON Semiconductor Corporation

Texas Instruments

Texas Instruments

Toshiba

Toshiba

Renesas Electronics

Renesas Electronics

ROHM Semiconductor

ROHM Semiconductor

Vishay Intertechnology Inc.

Vishay Intertechnology Inc.

Mitsubishi Electric Corporation

Mitsubishi Electric Corporation

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